**삼성전자 DX부문 현장실습 참가 신청서**

작성일 : 2023. 00. 00

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| **인****적****사****항** | **성명** |  | **영문성명** |  |
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| **대학교** | YYYY.MM | YYYY.MM |  | ※ 주전공, 복수전공, 연합전공 등이수예정 전공 모두 작성 |  | 0.0/0.0 |

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| **자****격****사****항** | **특수자격및면허** | **등급** |  | **어****학****사****항** | **영어** | 점(응시명) |  | **특****기****사****항** | **병역구분** | 필/미필/면제/비대상 |
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|  |  | **기타** |  | **보훈여부** | ( Y / N ) |

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| **지원 동기(500자 이상)** |  |
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| **장점과 단점(500자 이상)** |  |
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